



Intel® NUC Kit NUC8i7HNK

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Essentials

📄 Export specifications

Product Collection	Intel® NUC Kit with 8th Generation Intel® Core™ Processors
Code Name	Products formerly HADES CANYON
Status	Launched
Launch Date ?	Q1'18
Board Form Factor	UCFF (5.5" x 8")
Socket	Soldered-down BGA
Internal Drive Form Factor	M.2 SSD
# of Internal Drives Supported	2
Lithography ?	14 nm
TDP ?	65 W
DC Input Voltage Supported	19 VDC
Processor Included	Intel® Core™ i7-8705G Processor with Radeon™ RX Vega M GL graphics (8M Cache, up to 4.10 GHz)
Warranty Period	3 yrs



Supplemental Information

Embedded Options Available ?	No
Datasheet	View now
Description	Other features: Includes 2x Thunderbolt 3 (40Gbps) via rear USB-C ports, SDXC card slot and front USB-A and USB-C ports w/ USB 3.1 Gen 2






Memory & Storage

Max Memory Size (dependent on memory type) ?	32 GB
Memory Types ?	DDR4-2400+ 1.2V SO-DIMM
Max # of Memory Channels ?	2
Max Memory Bandwidth ?	38.4 GB/s
Max # of DIMMs ?	2
ECC Memory Supported ‡ ?	No

Processor Graphics

Integrated Graphics [‡] 	Yes
Graphics Output 	2x Mini-DP 1.2, 2x Thunderbolt 3, F+R HDMI 2.0a
# of Displays Supported [‡]	6
Discrete Graphics	Radeon™ RX Vega M GL graphics

Expansion Options

PCI Express Revision 	Gen3
PCI Express Configurations [‡] 	Dual M.2 slots with PCIe x4 lanes
Removable Memory Card Slot 	SDXC with UHS-I support
M.2 Card Slot (wireless) 	2230
M.2 Card Slot (storage) 	22x42/80, 22x80





I/O Specifications

# of USB Ports	13
USB Configuration	F: USB3, 2x USB 3.1g2 (Type A and C); R: 4x USB3, 2x Thunderbolt3 (USB3.1g2); INT: 2x USB2, 2x USB3
USB Revision 	2.0, 3.0, 3.1 Gen2
USB 2.0 Configuration (External + Internal)	0 + 2
USB 3.0 Configuration (External + Internal)	1F, 4R, 2i
Total # of SATA Ports 	2
Max # of SATA 6.0 Gb/s Ports	2
RAID Configuration 	2x M.2 SATA/PCIe SSD (RAID-0 RAID-1)
Audio (back channel + front channel)	7.1 digital; L+R+mic (F); L+R+TOSLINK (R)
Integrated LAN 	2x 10/100/1000
Integrated Wireless [‡]	Intel® Wireless-AC 8265 + Bluetooth 4.2
Integrated Bluetooth	Yes
Consumer Infrared Rx Sensor 	Yes
S/PDIF Out Connector	TOSLINK
Additional Headers 	CEC, 2x USB2.0, 2x USB 3.0, FRONT_PANEL
# of Thunderbolt™ 3 Ports 	2

Package Specifications

Low Halogen Options Available	No
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Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) [‡] 	Yes
Intel® vPro™ Platform Eligibility [‡] 	No
TPM 	No
Intel® HD Audio Technology 	Yes
Intel® Rapid Storage Technology 	Yes

Intel® Virtualization Technology (VT-x) ‡ ? Yes

Intel® Platform Trust Technology (Intel® PTT) ? Yes

Security & Reliability

Intel® AES New Instructions ? Yes

More support options for Intel® NUC Kit NUC8i7HNK



Product Support



Downloads and Software



Support Community



Warranty and
Replacement



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Refer to Datasheet for formal definitions of product properties and features.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.



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